



# P3M12080K3 SiC MOS N-Channel Enhancement Mode

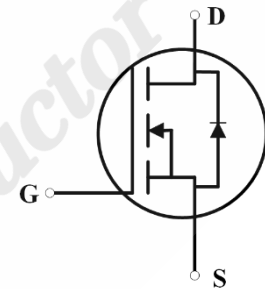
$V_{RRM}$	= 1200	V
$I_D$	= 38	A
$I_D (100^\circ\text{C})$	= 27	A
$R_{DS(on)}$	= 80	m $\Omega$

## SiC MOS P3M12080K3 N-Channel Enhancement Mode



### Features

- Qualified to AEC-Q101
- High Blocking Voltage with Low On-Resistance
- High-Frequency Operation
- Ultra-Small  $Q_{gd}$
- 100% UIS tested



### Benefits

- Improve System Efficiency
- Increase Power Density
- Reduce Heat Sink Requirements
- Reduction of System Cost

TO-247-3

Gate	1
Drain	2
Source	3

### Applications

- Solar Inverters
- EV Battery Chargers
- High Voltage DC/DC Converters
- Switch Mode Power Supplies



### Order Information

Part Number	Package	Marking
P3M12080K3	TO-247-3	P3M12080K3



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PN Junction Semiconductor



# P3M12080K3 SiC MOS

## N-Channel Enhancement Mode

### 1. Maximum Ratings

At  $T_J = 25^\circ\text{C}$ , unless specified otherwise

Parameter	Symbol	Value	Unit	Test Conditions
Drain - Source Voltage	$V_{DSmax}$	1200	V	$V_{GS} = 0V$ $I_D = 100\mu A$
Gate - Source Voltage (dynamic)	$V_{GSmax}$	-8 / +21	V	AC (f > 1Hz)
Gate - Source Voltage(static) turn-on gate voltage turn-off gate voltage	$V_{GS,on}$ $V_{GS,off}$	+15 / +18 -3	V	Static
Continuous Drain Current	$I_D$	38	A	$V_{GS} = 15V$ $T_C = 25^\circ\text{C}$
		27		$V_{GS} = 15V$ $T_C = 100^\circ\text{C}$
Pulsed Drain Current	$I_{D(pulse)}$	80	A	
Power Dissipation	$P_D$	221	W	
Operating Junction	$T_J$	-55 To +175	$^\circ\text{C}$	
Storage Temperature	$T_{stg}$	-55 To +175	$^\circ\text{C}$	
Solder Temperature	$T_L$	260	$^\circ\text{C}$	
Mounting Torque	$M_d$	1 8.8	Nm lbf-in	M3 or 6-32 screw

## 2. Electrical Characteristics

At  $T_J = 25^\circ\text{C}$ , unless specified otherwise

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Drain-Source Breakdown Voltage	$V_{(BR)DSS}$	1200	/	/	V	$V_{GS} = 0V$ $I_D = 100\mu A$
Gate Threshold Voltage	$V_{GS(th)}$	1.8	2.4	/	V	(tested after 30ms pulse at $V_{GS} = 15V$ ) $V_{DS} = V_{GS}$ $I_D = 5mA$ $T_J = 25^\circ\text{C}$
		/	1.6	/	V	$V_{DS} = V_{GS}$ $I_D = 5mA$ $T_J = 175^\circ\text{C}$
Zero Gate Voltage Drain Current	$I_{DSS}$	/	1.8	100	$\mu A$	$V_{GS} = 0V$ $V_{DS} = 1200V$
Gate-Source Leakage Current	$I_{GSS}$	/	20	250	nA	$V_{GS} = 15V$ $V_{DS} = 0V$
Drain-Source On-State Resistance	$R_{DS(on)}$	/	80	104	m $\Omega$	$V_{GS} = 15V$ $I_D = 20A$ $T_J = 25^\circ\text{C}$
		/	104	/		$V_{GS} = 15V$ $I_D = 20A$ $T_J = 175^\circ\text{C}$
		/	66	/		$V_{GS} = 18V$ $I_D = 20A$ $T_J = 25^\circ\text{C}$



# P3M12080K3 SiC MOS

## N-Channel Enhancement Mode

Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Transconductance	$g_{fs}$	/	10	/	S	$V_{DS} = 20V$ $I_{DS} = 20A$ $T_J = 25^\circ C$
		/	9.6	/		$V_{DS} = 20V$ $I_{DS} = 20A$ $T_J = 175^\circ C$
Input Capacitance	$C_{iss}$	/	2032	/	pF	$V_{GS} = 0V$ $V_{DS} = 800V$ $f = 1MHz$ $V_{AC} = 25mV$
Output Capacitance	$C_{oss}$	/	73.6	/		
Reverse Transfer Capacitance	$C_{rss}$	/	6	/		
Coss Stored Energy	$E_{oss}$	/	52.9	/	$\mu J$	
Turn-on Energy	$E_{on}$	/	507	/	$\mu J$	$V_{DS} = 800V$ $V_{GS} = -3/15V$ $I_D = 20A$ $R_G = 1\Omega$
Turn-off Energy	$E_{off}$	/	27	/		
Turn-on Energy	$E_{on}$	/	405	/	$\mu J$	$V_{DS} = 800V$ $V_{GS} = -3/18V$ $I_D = 20A$ $R_G = 1\Omega$
Turn-off Energy	$E_{off}$	/	33	/		
Turn-On Delay Time	$t_{d(on)}$	/	17	/	ns	$V_{DS} = 800V$ $V_{GS} = -3/15V$ $I_D = 20A$ $R_G = 1\Omega$
Rise Time	$t_r$	/	32	/		
Turn-Off Delay Time	$t_{d(off)}$	/	23	/		
Fall Time	$t_f$	/	18	/		
Internal Gate Resistance	$R_{G(int)}$	/	3.5	/	$\Omega$	$f = 1MHz$ $V_{AC} = 25mV$



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Parameter	Symbol	Value			Unit	Test Conditions
		Min.	Typ.	Max.		
Gate to Source Charge	$Q_{gs}$	/	22.2	/	nC	$V_{DS} = 800V$ $I_{DS} = 20A$ $V_{GS} = -3 \text{ to } 15V$ $I_G = 20mA$
Gate to Drain Charge	$Q_{gd}$	/	12.3	/		
Total Gate Charge	$Q_g$	/	54.6	/		

## 3. Reverse Diode Characteristics

At  $T_J = 25^\circ C$ , unless specified otherwise

Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Diode Forward Voltage	$V_{SD}$	5.2	/	V	$V_{GS} = -3V$ $I_{SD} = 10A$ $T_J = 25^\circ C$
		4.8	/	V	$V_{GS} = -3V$ $I_{SD} = 10A$ $T_J = 175^\circ C$
Continuous Diode Forward Current	$I_S$	31	/	A	$V_{GS} = -3V$
Reverse Recover Time	$t_{rr}$	33	/	ns	$V_{GS} = -3V$ $I_{SD} = 20A$ $V_R = 800V$ $d_{if}/d_t = 3800A/\mu s$ $T_J = 25^\circ C$
Reverse Recovery Charge	$Q_{rr}$	348	/	nC	
Peak Reverse Recovery Current	$I_{rrm}$	17	/	A	

Parameter	Symbol	Value		Unit	Test Conditions
		Typ.	Max.		
Reverse Recover Time	$t_{rr}$	28	/	ns	$V_{GS} = -3V$ $I_{SD} = 20A$ $V_R = 800V$ $di_f/dt = 4000A/\mu s$ $T_J = 25^\circ C$
Reverse Recovery Charge	$Q_{rr}$	393	/	nC	
Peak Reverse Recovery Current	$I_{rrm}$	23	/	A	

### 4. Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction to Case	$R_{\theta JC}$	0.68	$^\circ C/W$

### 5. Typical Performance

At  $T_J = 25^\circ C$ , unless specified otherwise

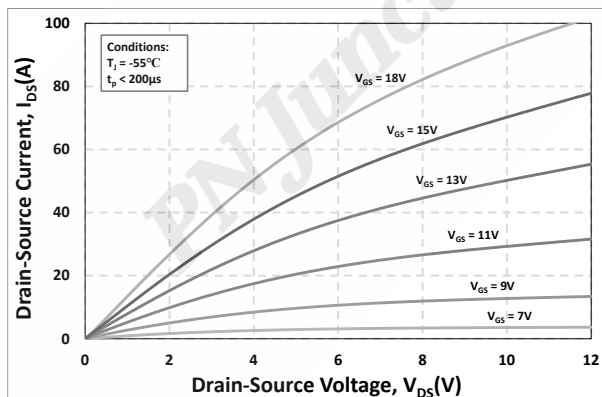


Figure 1. Output Characteristics  $T_J = -55^\circ C$

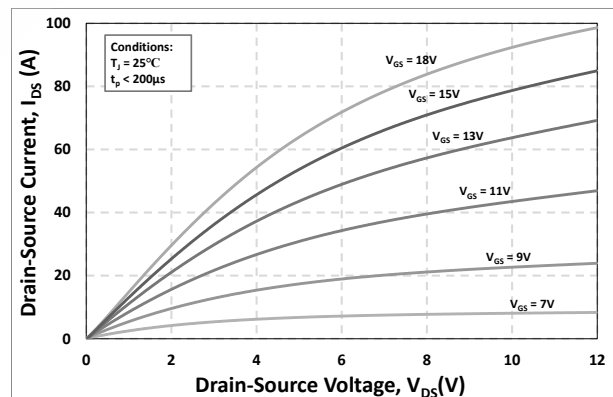


Figure 2. Output Characteristics  $T_J = 25^\circ C$

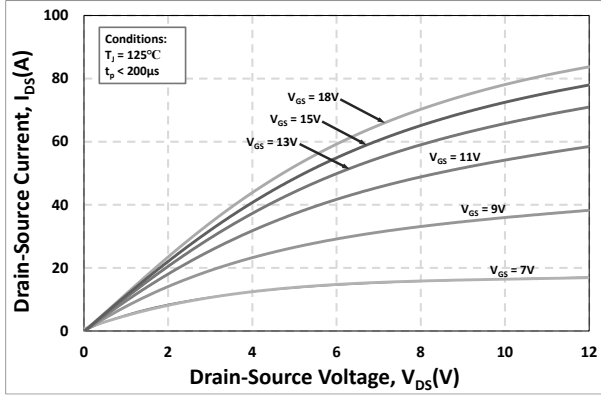


Figure 3. Output Characteristics  $T_J = 125^\circ\text{C}$

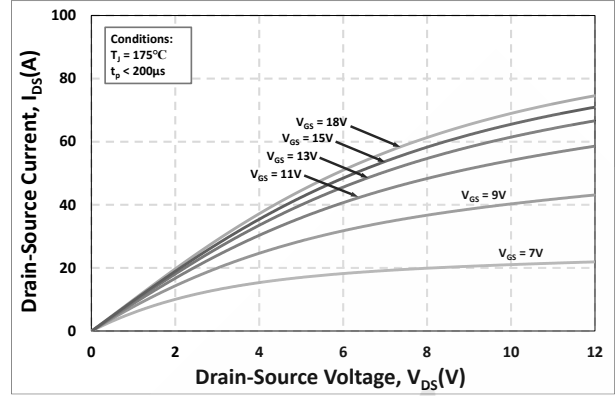


Figure 4. Output Characteristics  $T_J = 175^\circ\text{C}$

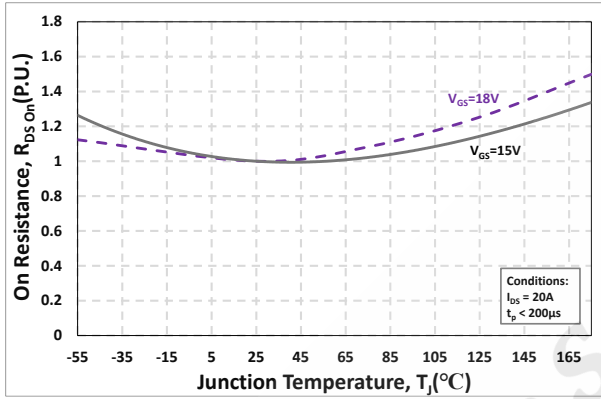


Figure 5. Normalized On-Resistance vs. Temperature

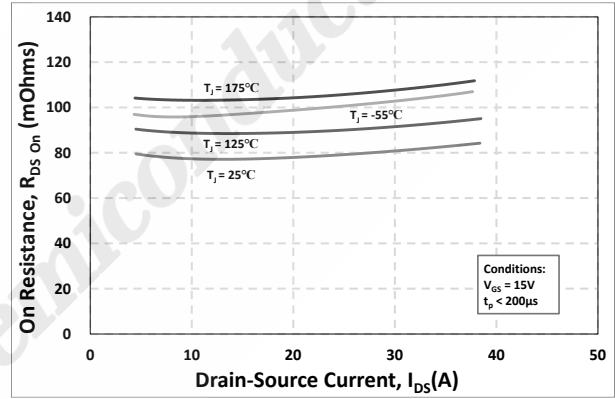


Figure 6. On-Resistance vs. Drain Current Various Temperatures

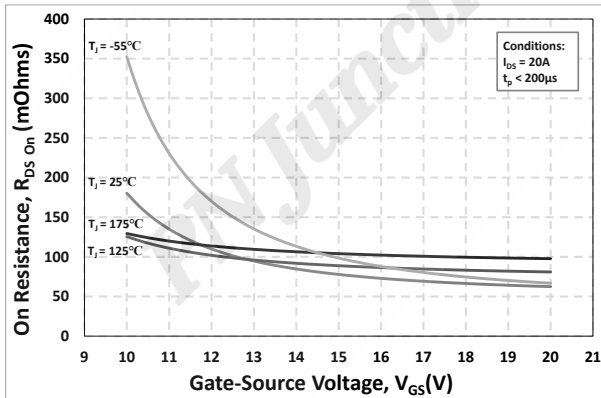


Figure 7. On-Resistance vs. Gate-Source Voltage

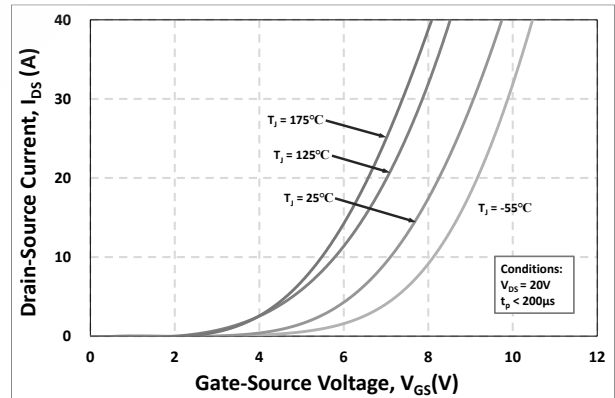


Figure 8. Transfer Characteristic for Various Junction Temperatures



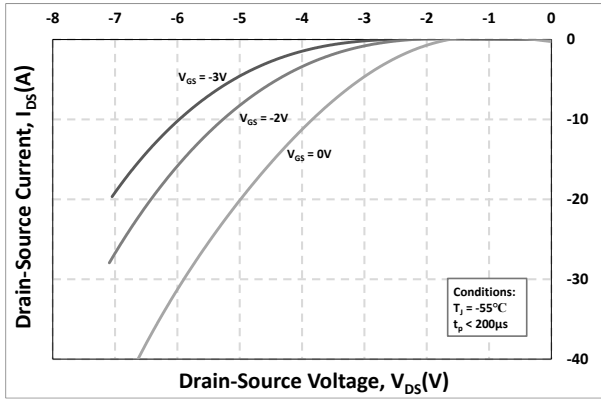


Figure 9. Body Diode Characteristic at  $-55^\circ\text{C}$

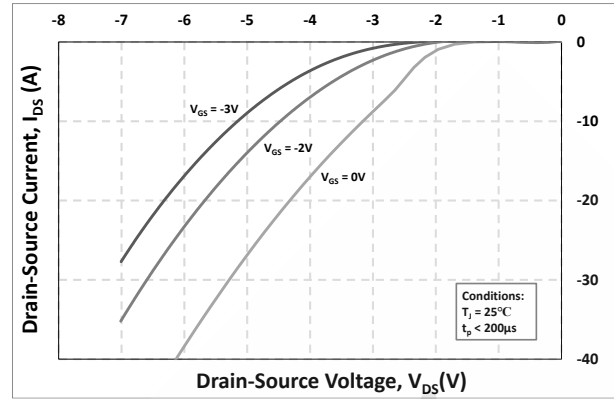


Figure 10. Body Diode Characteristic at  $25^\circ\text{C}$

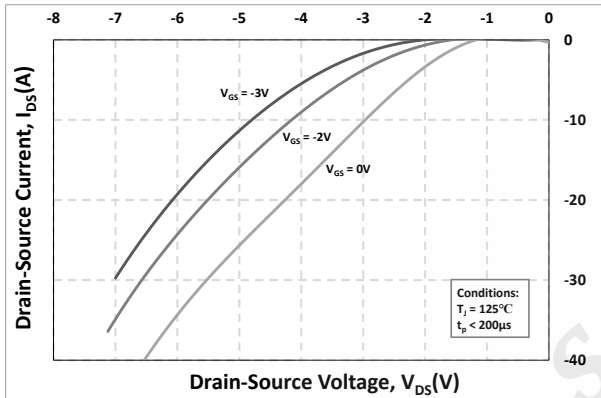


Figure 11. Body Diode Characteristic at  $125^\circ\text{C}$

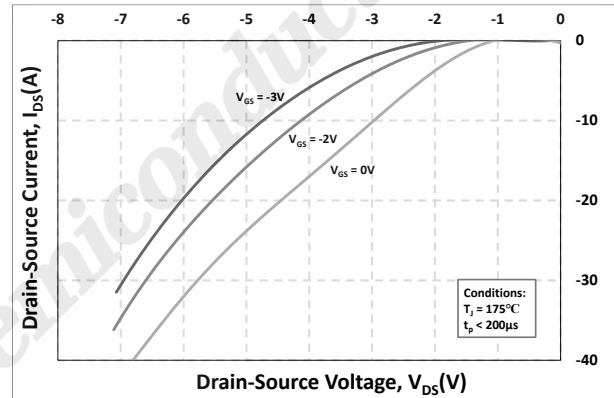


Figure 12. Body Diode Characteristic at  $175^\circ\text{C}$

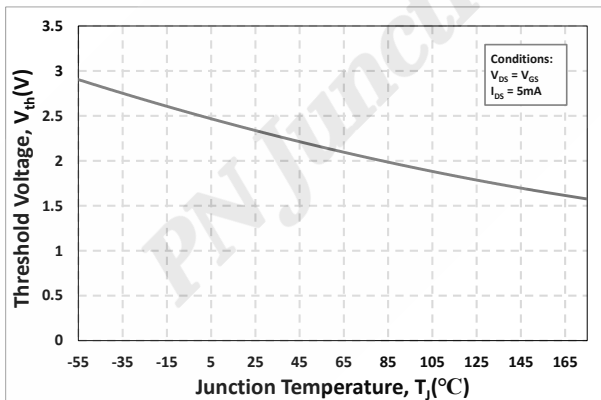


Figure 13. Threshold Voltage vs. Temperature

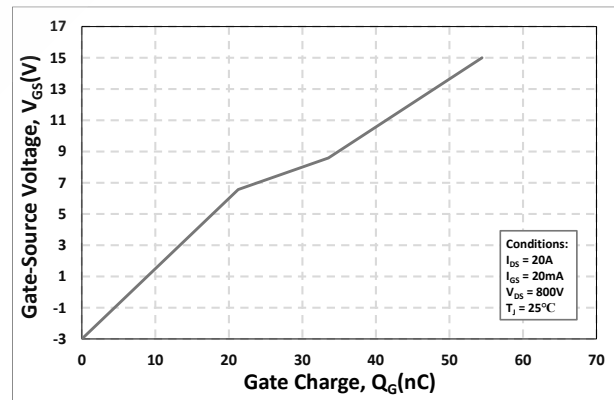


Figure 14. Gate Charge Characteristics

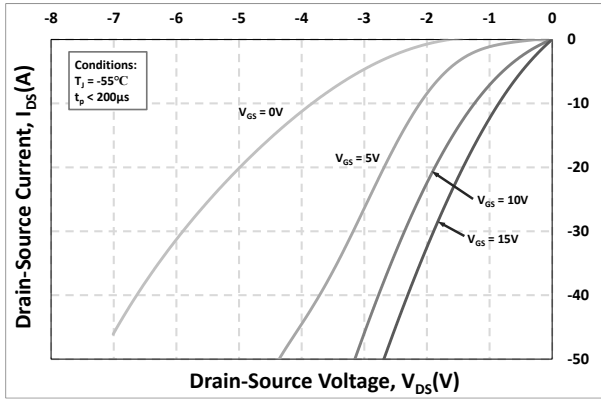


Figure 15. 3rd Quadrant Characteristic at -55°C

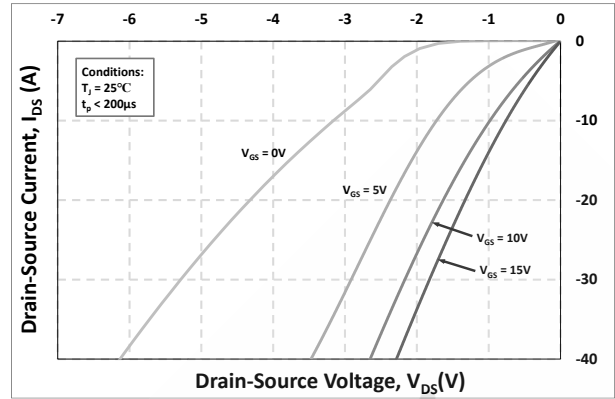


Figure 16. 3rd Quadrant Characteristic at 25°C

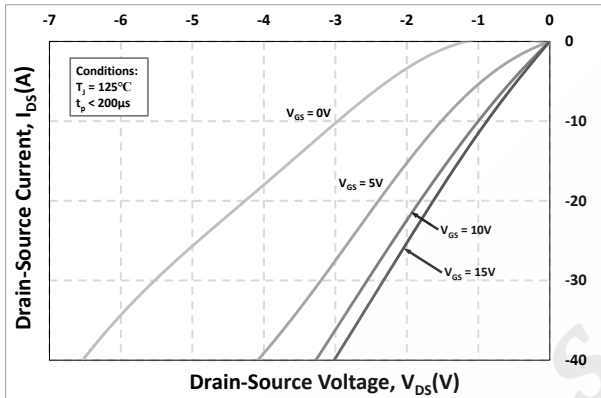


Figure 17. 3rd Quadrant Characteristic at 125°C

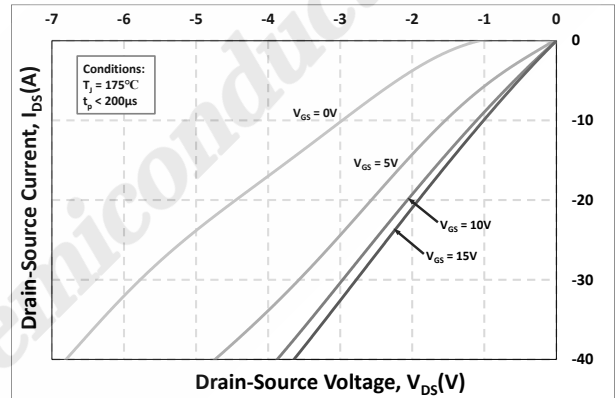


Figure 18. 3rd Quadrant Characteristic at 175°C

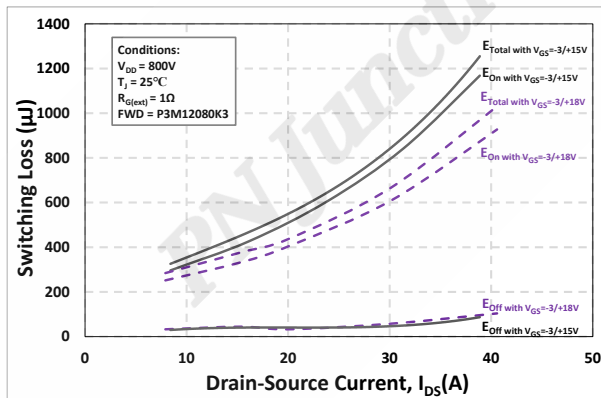


Figure 19. Clamped Inductive Switching Energy vs. Drain Current ( $V_{DD} = 800V$ )

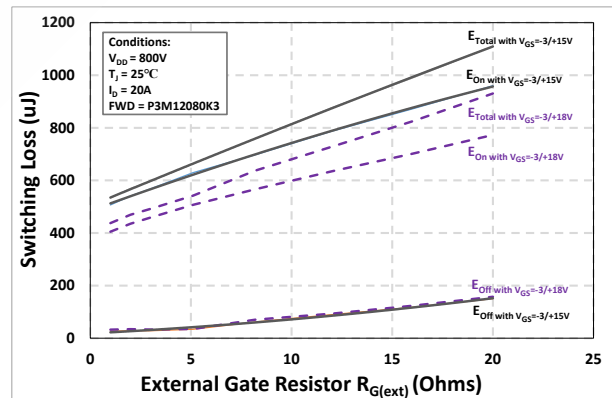


Figure 20. Clamped Inductive Switching Energy vs.  $R_{G(ext)}$

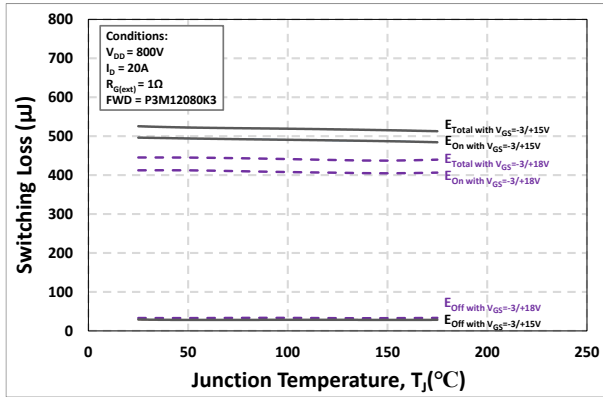


Figure 21. Clamped Inductive Switching Energy vs. Temperature

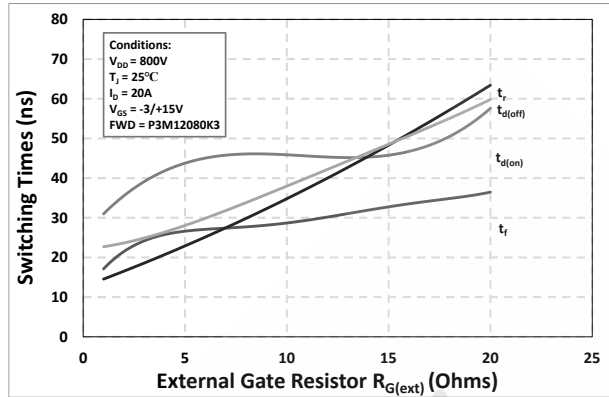


Figure 22. Switching Times vs.  $R_{G(ext)}$

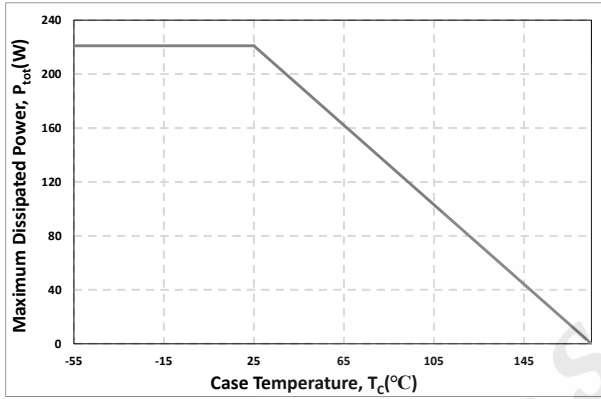


Figure 23. Maximum Power Dissipation Derating vs. Case Temperature

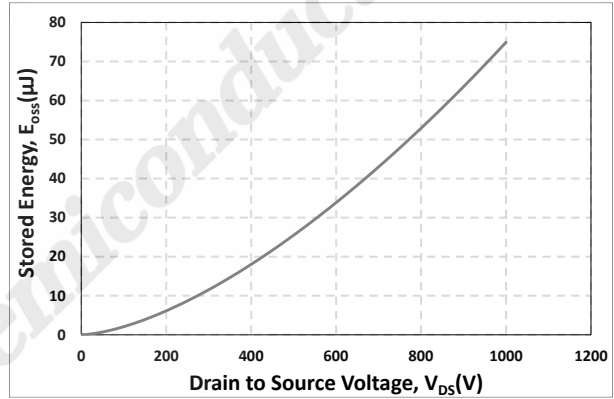


Figure 24. Output Capacitor Stored Energy

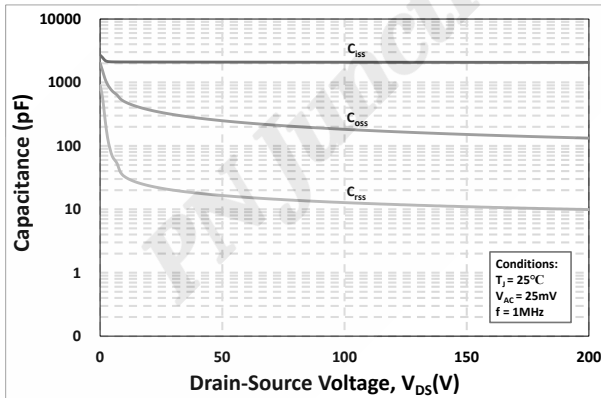


Figure 25. Capacitances vs. Drain-Source Voltage (0 - 200V)

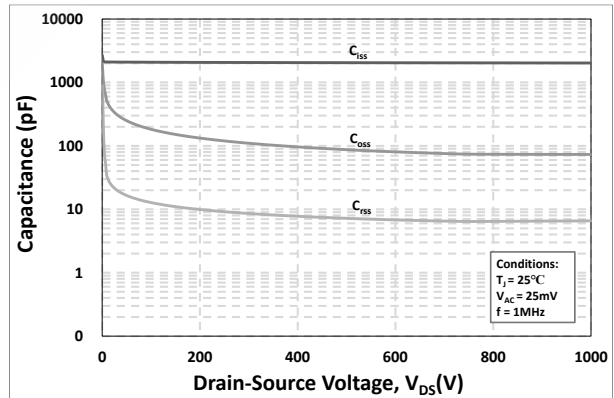


Figure 26. Capacitances vs. Drain-Source Voltage (0 - 1000V)

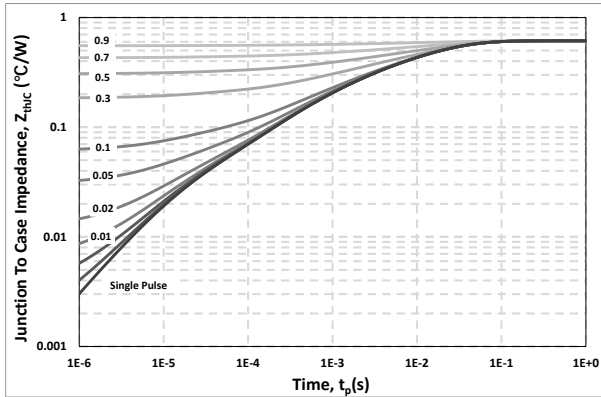


Figure 27. Transient Thermal Impedance (Junction - Case)

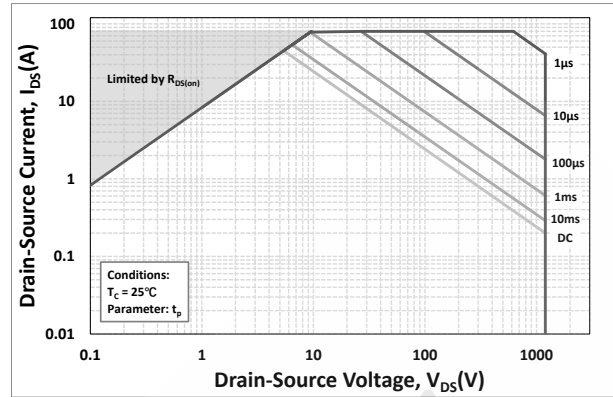


Figure 28. Safe Operating Area

## 6. Definitions

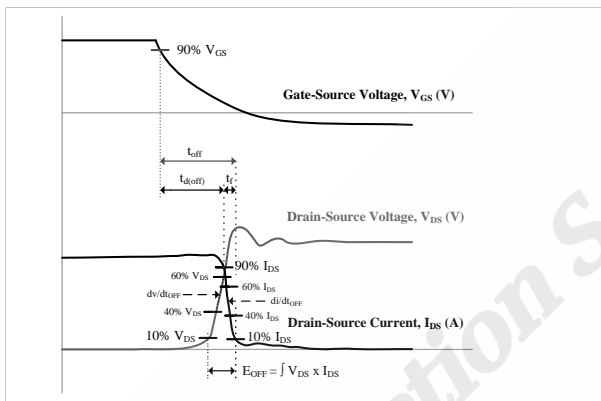


Figure 29. Turn-off Transient Definitions

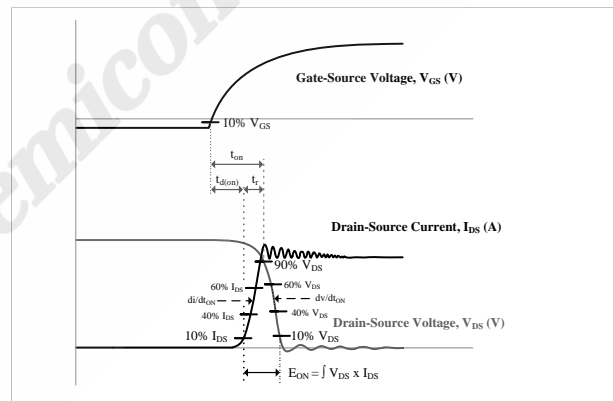


Figure 30. Turn-on Transient Definitions

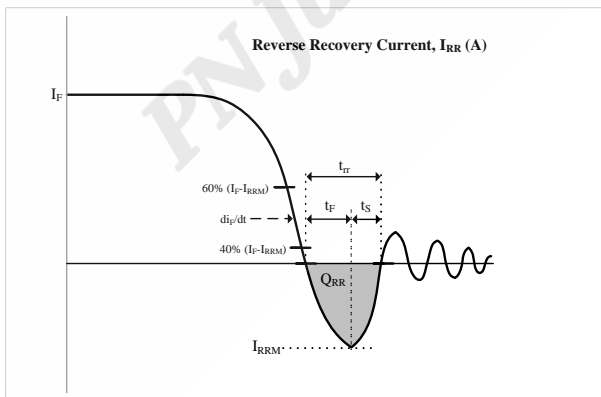


Figure 31. Reverse Recovery Definitions

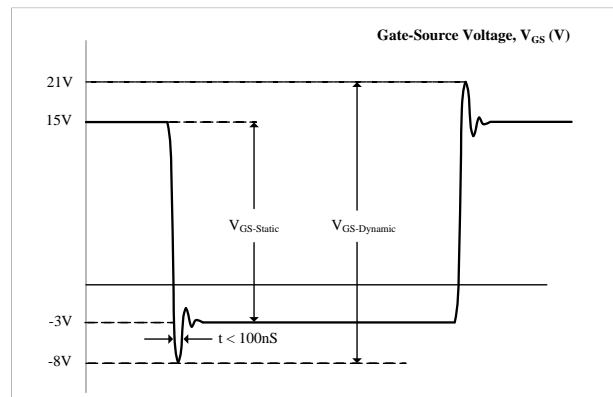
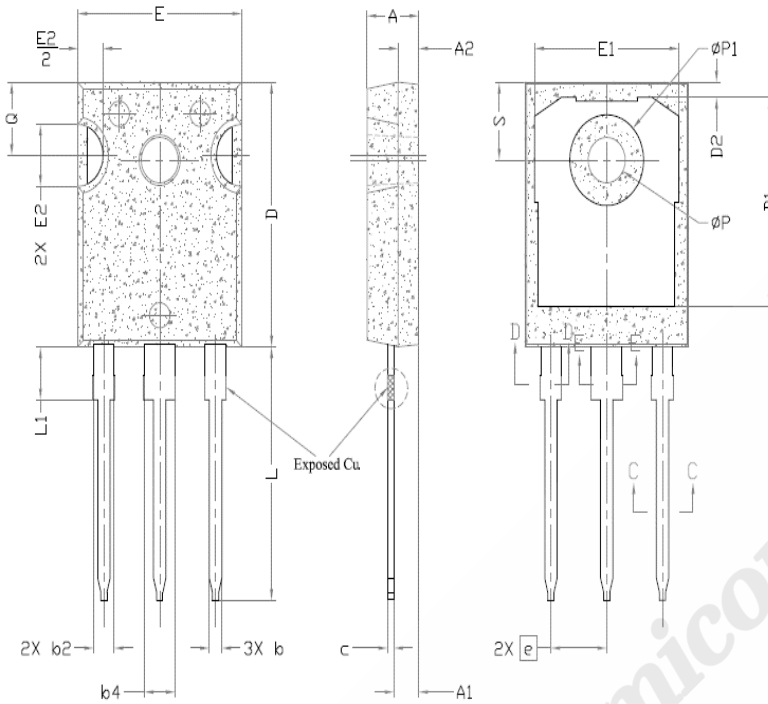


Figure 32. v<sub>GS</sub> Transient Definitions

## 7. Package Outlines



SYMBOL	DIMENSIONS			NOTES
	MIN.	NOM.	MAX.	
A	4,83	5,02	5,21	
A1	2,29	2,41	2,55	
A2	1,50	2,00	2,49	
b	1,12	1,20	1,33	
b1	1,12	1,20	1,28	
b2	1,91	2,00	2,39	6
b3	1,91	2,00	2,34	
b4	2,87	3,00	3,22	6, 8
b5	2,87	3,00	3,18	
c	0,55	0,60	0,69	6
c1	0,55	0,60	0,65	
D	20,80	20,95	21,10	4
D1	16,25	16,55	17,65	5
D2	0,51	1,19	1,35	
E	15,75	15,94	16,13	4
E1	13,46	14,02	14,16	5
E2	4,32	4,91	5,49	3
e	5,44BSC			
L	19,81	20,07	20,32	
L1	4,10	4,19	4,40	6
ØP	3,56	3,61	3,65	7
ØP1	7,19REF.			
Q	5,39	5,79	6,20	
S	6,04	6,17	6,30	

Drawing and Dimensions

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